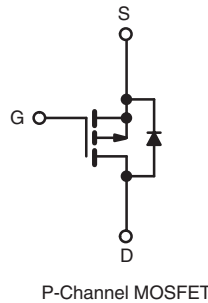


Power MOSFET

PRODUCT SUMMARY

| | | |
|---------------------------|------------------|------|
| V_{DS} (V) | - 100 | |
| $R_{DS(on)}$ (Ω) | $V_{GS} = -10$ V | 0.20 |
| Q_g (Max.) (nC) | 61 | |
| Q_{gs} (nC) | 14 | |
| Q_{gd} (nC) | 29 | |
| Configuration | Single | |

TO-220 FULLPAK


FEATURES

- Isolated Package
- High Voltage Isolation = 2.5 kV_{RMS} (t = 60 s; f = 60 Hz)
- Sink to Lead Creepage Dist. = 4.8 mm
- P-Channel
- 175 °C Operating Temperature
- Dynamic dV/dt
- Low Thermal Resistance
- Lead (Pb)-free Available


RoHS*
COMPLIANT

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

ORDERING INFORMATION

| | |
|----------------|-------------------------------|
| Package | TO-220 FULLPAK |
| Lead (Pb)-free | IRFI9540GPbF SiHFI9540G-E3 |
| SnPb | IRFI9540G SiHFI9540G |

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted

| PARAMETER | SYMBOL | LIMIT | UNIT |
|--|------------------|----------------------------------|----------|
| Drain-Source Voltage | V_{DS} | - 100 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | |
| Continuous Drain Current | I_D | V_{GS} at - 10 V $T_C = 25$ °C | - 11 |
| | | $T_C = 100$ °C | - 7.6 |
| Pulsed Drain Current ^a | I_{DM} | - 44 | A |
| Linear Derating Factor | | 0.32 | W/°C |
| Single Pulse Avalanche Energy ^b | E_{AS} | 600 | mJ |
| Repetitive Avalanche Current ^a | I_{AR} | - 11 | A |
| Repetitive Avalanche Energy ^a | E_{AR} | 4.8 | mJ |
| Maximum Power Dissipation | P_D | 48 | W |
| | | $T_C = 25$ °C | |
| Peak Diode Recovery dV/dt ^c | dV/dt | - 5.5 | V/ns |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to + 175 | °C |
| Soldering Recommendations (Peak Temperature) | for 10 s | 300 ^d | |
| Mounting Torque | 6-32 or M3 screw | 10 | lbf · in |
| | | 1.1 | N · m |

Notes

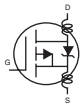
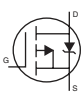
- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = -25$ V, starting $T_J = 25$ °C, L = 7.4 mH, $R_G = 25$ Ω , $I_{AS} = -11$ A (see fig. 12).
- $I_{SD} \leq -19$ A, $dI/dt \leq 170$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 175$ °C.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS

| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
|----------------------------------|------------|------|------|------|
| Maximum Junction-to-Ambient | R_{thJA} | - | 65 | °C/W |
| Maximum Junction-to-Case (Drain) | R_{thJC} | - | 3.1 | |

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|--|---------------------|---|------|--------|-----------|---------------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$ | -100 | - | - | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}$, $I_D = -1\text{ mA}$ | - | -0.087 | - | V/°C |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$ | -2.0 | - | -4.0 | V |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = \pm 20\text{ V}$ | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$ | - | - | -100 | μA |
| | | $V_{DS} = -80\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$ | - | - | -500 | |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS} = -10\text{ V}$ $I_D = -6.6\text{ A}^b$ | - | - | 0.20 | Ω |
| Forward Transconductance | g_{fs} | $V_{DS} = -50\text{ V}, I_D = -6.6\text{ A}^b$ | 5.4 | - | - | S |
| Dynamic | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V},$ $V_{DS} = -25\text{ V},$ $f = 1.0\text{ MHz}$, see fig. 5 | - | 1400 | - | pF |
| Output Capacitance | C_{oss} | | - | 590 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 140 | - | |
| Drain to Sink Capacitance | C | $f = 1\text{ MHz}$ | - | 12 | - | |
| Total Gate Charge | Q_g | $V_{GS} = -10\text{ V}$ $I_D = -19\text{ A}, V_{DS} = -80\text{ V},$ see fig. 6 and 13 ^b | - | - | 61 | nC |
| Gate-Source Charge | Q_{GS} | | - | - | 14 | |
| Gate-Drain Charge | Q_{GD} | | - | - | 29 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -50\text{ V}, I_D = -19\text{ A},$ $R_G = 9.1\text{ }\Omega, R_D = 7.4\text{ }\Omega,$ see fig. 10 ^b | - | 24 | - | ns |
| Rise Time | t_r | | - | 110 | - | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 51 | - | |
| Fall Time | t_f | | - | 86 | - | |
| Internal Drain Inductance | L_D | Between lead, 6 mm (0.25") from package and center of die contact | - | 4.5 | - | nH |
| Internal Source Inductance | L_S |  | - | 7.5 | - | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source-Drain Diode Current | I_S | MOSFET symbol showing the integral reverse p - n junction diode | - | - | -11 | A |
| Pulsed Diode Forward Current ^a | I_{SM} |  | - | - | -44 | |
| Body Diode Voltage | V_{SD} | $T_J = 25\text{ }^\circ\text{C}, I_S = -11\text{ A}, V_{GS} = 0\text{ V}^b$ | - | - | -4.2 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $T_J = 25\text{ }^\circ\text{C}, I_F = -19\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$ | - | 130 | 260 | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | | - | 0.35 | 0.70 | μC |
| Forward Turn-On Time | t_{on} | Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D) | | | | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

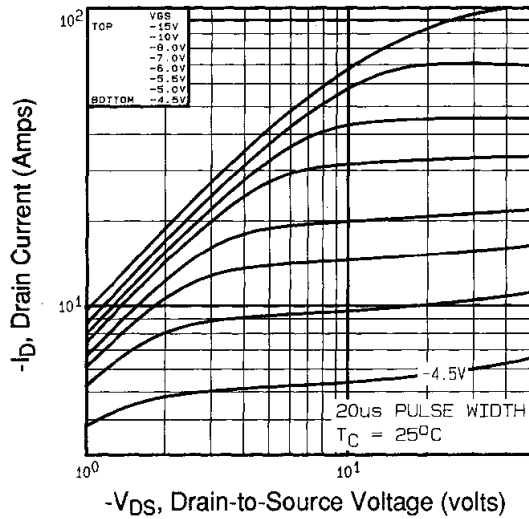


Fig. 1 - Typical Output Characteristics, $T_C = 25^\circ\text{C}$

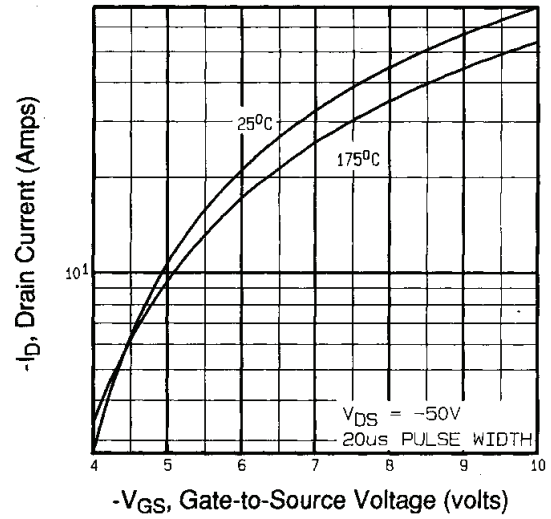


Fig. 3 - Typical Transfer Characteristics

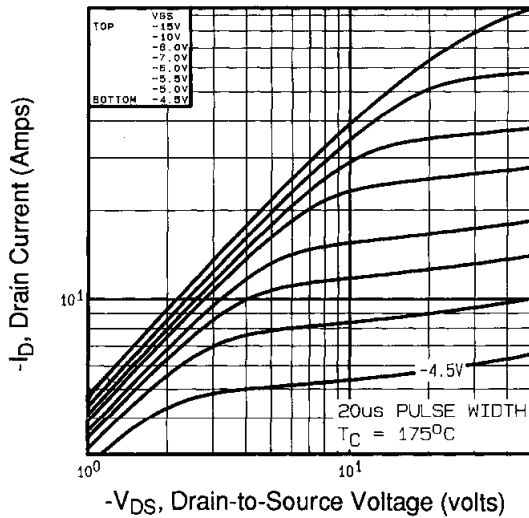


Fig. 2 - Typical Output Characteristics, $T_C = 175^\circ\text{C}$

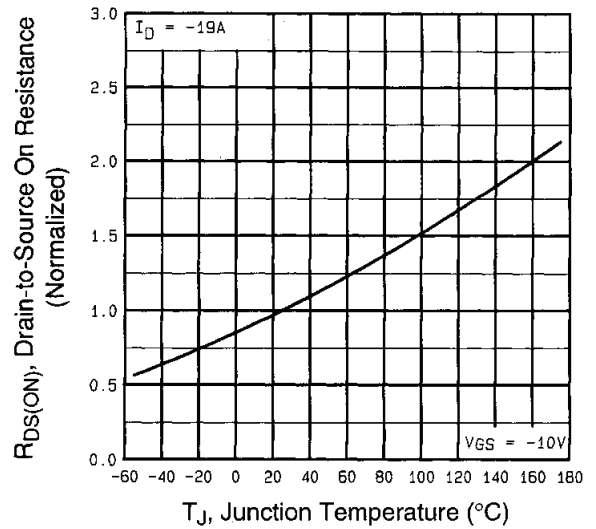


Fig. 4 - Normalized On-Resistance vs. Temperature

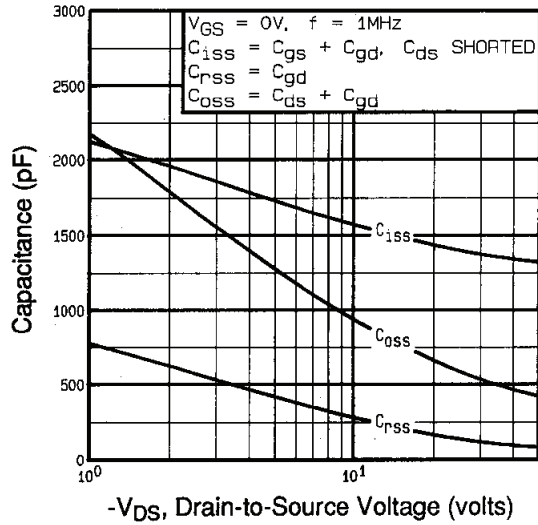


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

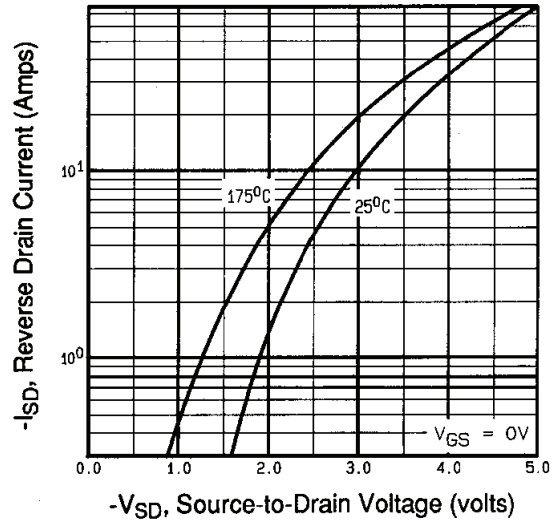


Fig. 7 - Typical Source-Drain Diode Forward Voltage

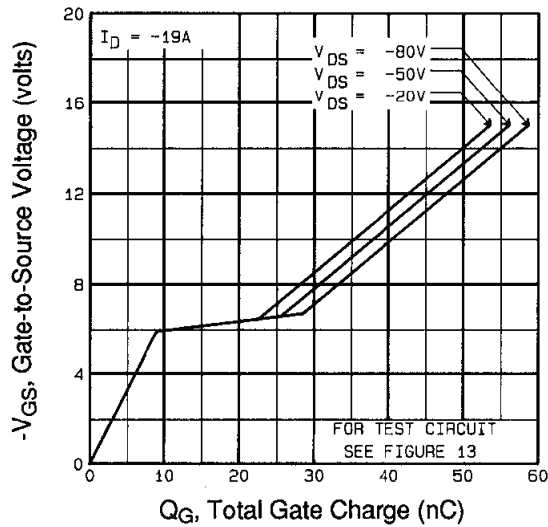


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

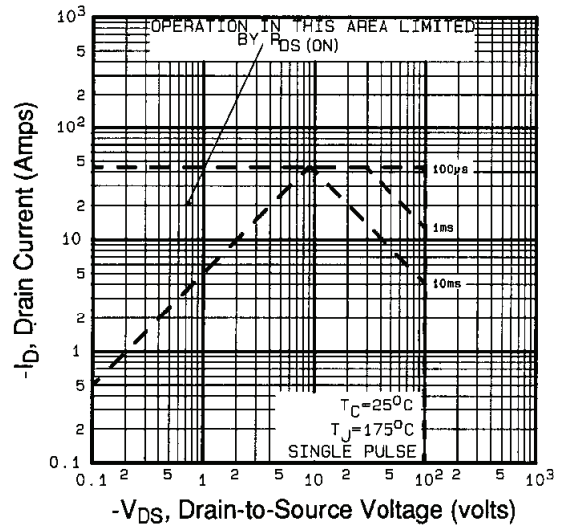


Fig. 8 - Maximum Safe Operating Area

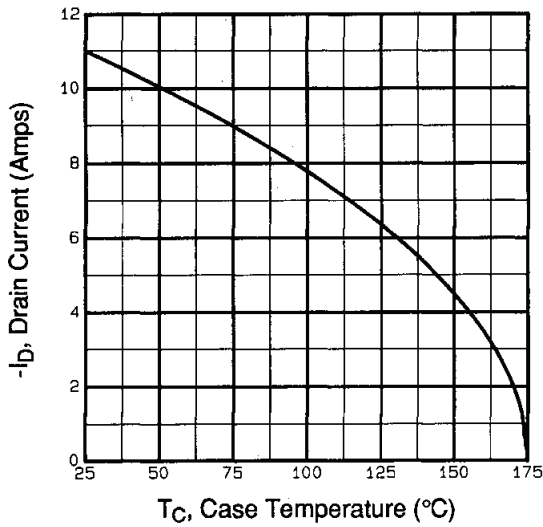


Fig. 9 - Maximum Drain Current vs. Case Temperature

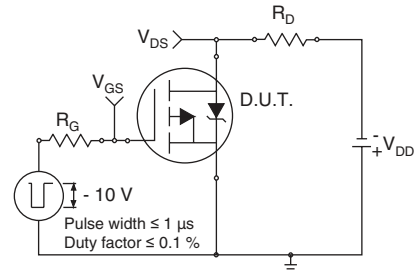


Fig. 10a - Switching Time Test Circuit

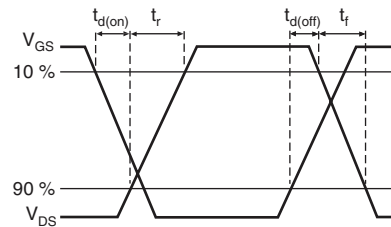


Fig. 10b - Switching Time Waveforms

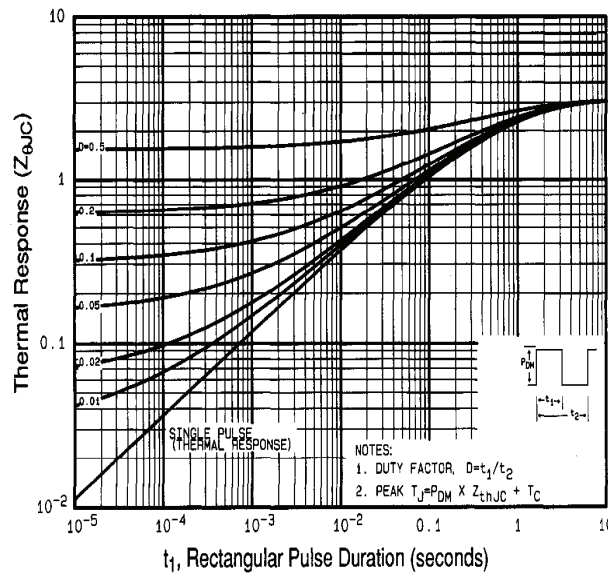


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

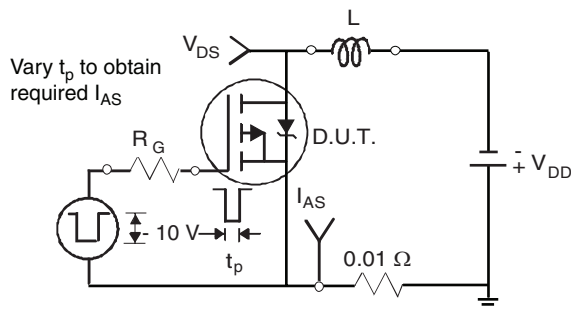


Fig. 12a - Unclamped Inductive Test Circuit

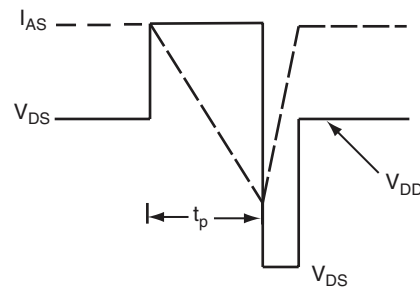


Fig. 12b - Unclamped Inductive Waveforms

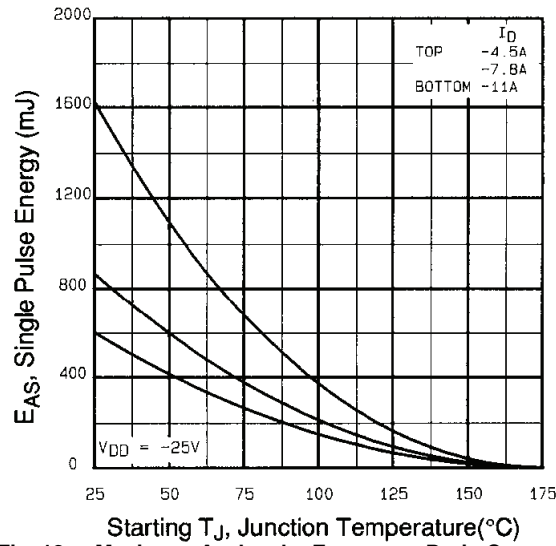


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

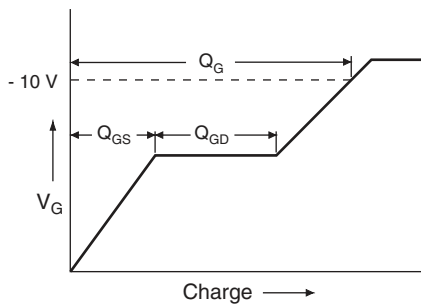


Fig. 13a - Basic Gate Charge Waveform

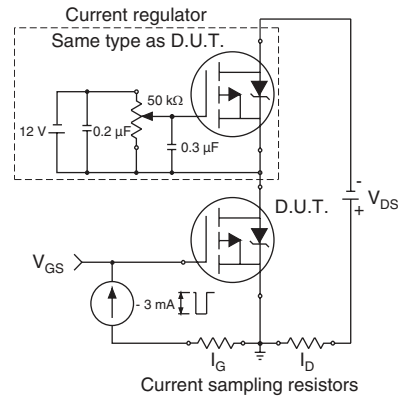
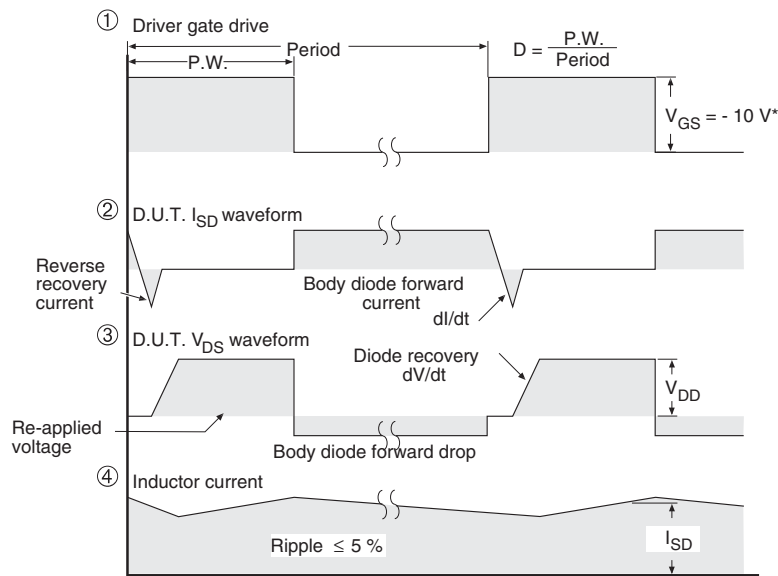
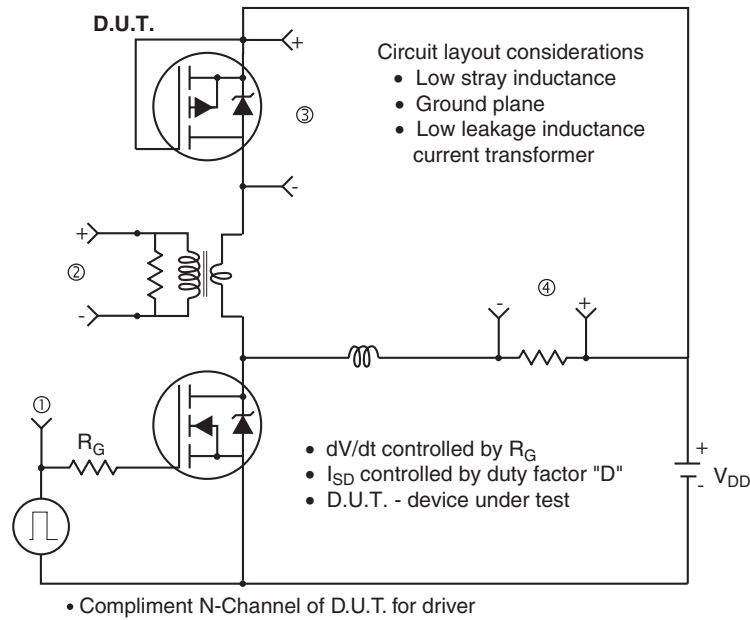


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



* $V_{GS} = -5\text{ V}$ for logic level and -3 V drive devices

Fig. 14 - For P-Channel

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